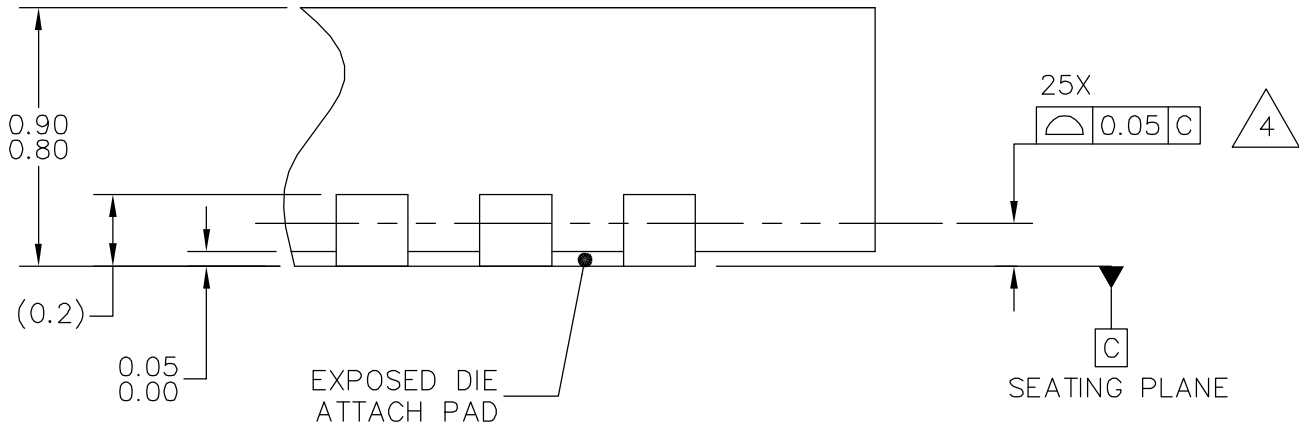


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TITLE: QFN (SAW), THERMALLY ENHANCED 4 X 4 X 0.85, 0.5 PITCH, 24 TERMINAL	DOCUMENT NO: 98ASA00651D	REV: A
	STANDARD: NON-JEDEC	
	SOT616-6	13 JAN 2016



DETAIL F
VIEW ROTATED 90°CW

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	STANDARD: NON-JEDEC	
	SOT616-6	13 JAN 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS DIMENSION APPLIES TO METALIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP. THIS DIMENSION SHOULD NOT BE MEASURED IN THE RADIUS AREA ON THE OTHER END OF THE TERMINAL.
4. BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.

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